



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit: 2827  
Examiner: J. ALCALA

In Re PATENT APPLICATION Of:

Applicant(s): Mark J. BAILEY et al.

Serial No.: 09/651,334

Filed: August 31, 2000

For: ENHANCED SURFACE LAMINAR  
CIRCUIT BOARD

Docket No.: ROC9-2000-0158-IBM-191

AMENDMENT

February 12, 2003

Assistant Commissioner of Patents  
Washington, D.C. 20231

Sir:

In response to the Examiner's Action mailed on December 4, 2002, please  
amend the application as follows:

**IN THE CLAIMS:**

Claim 1. (Amended) A surface laminar circuit board, comprising:  
an insulating layer;  
a conductive layer disposed on an upper surface of said insulating layer, said  
conductive layer having a hole formed therein;  
a dielectric layer disposed on an upper surface of the conductive layer; and  
a conductive pad having [a majority] over 50% thereof within an area defined by  
an outer periphery of the hole, said conductive pad being for receiving a surface  
mounted component thereon.

FEE ENCLOSED:\$  
Please charge any further  
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